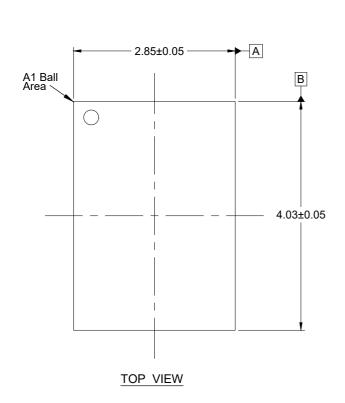
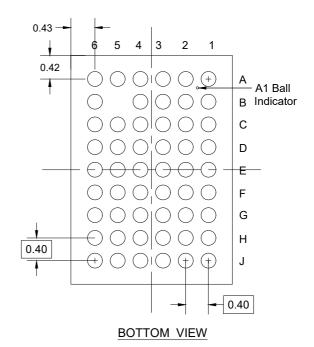
Package Outline Drawing

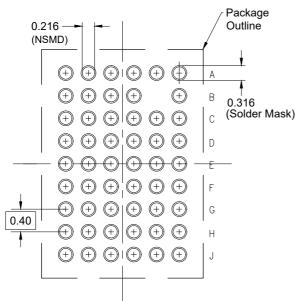


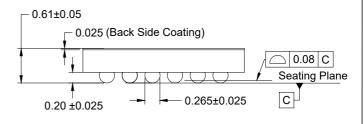
Package Code: AHR53

53-DSBGA 2.85 x 4.03 x 0.6 mm Body, 0.4mm Pitch PSC-4948-01, Revision: 00, Date Created: Feb 23, 2022









SIDE VIEW

NOTES:

- JEDEC compatible.
- All dimensions are in mm and angles are in degrees.
- Use ±0.05 mm for the non-toleranced dimensions.
- 4. Numbers in () are for references only.
- 5. Pre-reflow solderball diameter is Ø0.25 mm.
- UBM diameter is Ø0.24 mm.

Recommended Land Pattern (PCB Top View, SMD Design)